

Code	CII
Company name	Hochiminh City Infrastructure Investment Joint Stock Company
Date	12/28/2018
Subject	Record date for bonds interest payment

Content:

On December 27, 2018, Hochiminh City Infrastructure Investment Joint Stock Company announces the record date for bonds interest payment as follows:

1. Bond name: CII072019

- Bond code: CII11803
- Record date: January 14, 2019
- Reason and purpose: to pay for bond interest from July 27, 2018 to January 27, 2019
- Payment date: January 28, 2019
- Place of payment:
 - + Shareholders whose bonds have been deposited: at the securities firms where the bonds have been deposited.
 - + Shareholders whose bonds have not been deposited: at Techcom Securities Joint Stock Company (TCBS).

2. Bond name: CII_BOND2017-03

- Bond code: CII11709
- Record date: January 14, 2019
- Reason and purpose: to pay for bond interest from October 26, 2018 to January 26, 2019
- Payment date: January 28, 2019
- Place of payment:
 - + Shareholders whose bonds have been deposited: at the securities firms where the bonds have been deposited.
 - + Shareholders whose bonds have not been deposited: at Techcom Securities Joint Stock Company (TCBS).